



**THE DATASHEET OF  
CY7C1399BN-15ZXI**



# 256K (32K x 8) Static RAM

## Features

- **Temperature Ranges**
  - Industrial: -40°C to 85°C
  - Automotive-A: -40°C to 85°C
- **Single 3.3V power supply**
- **Ideal for low-voltage cache memory applications**
- **High speed: 12 ns**
- **Low active power**
  - 180 mW (max.)
- **Low-power alpha immune 6T cell**
- **Available in Pb-free and non Pb-free Plastic SOJ and TSOP I packages**

## Functional Description<sup>[1]</sup>

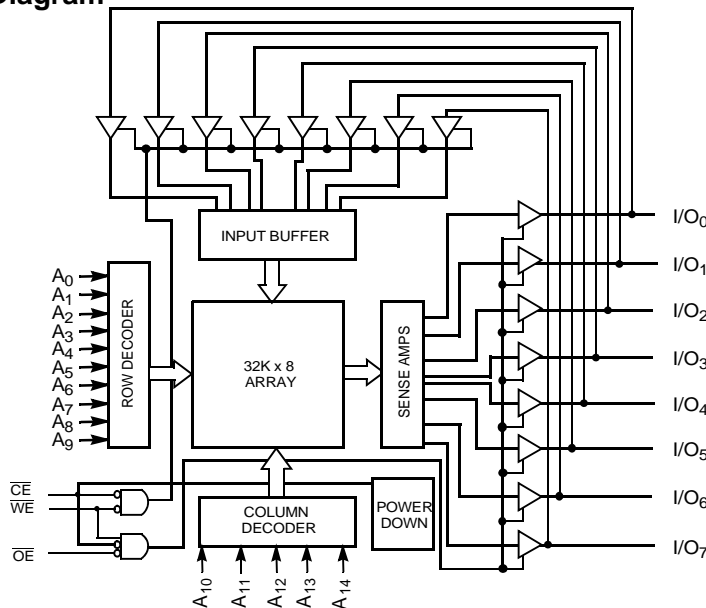
The CY7C1399BN is a high-performance 3.3V CMOS Static RAM organized as 32,768 words by 8 bits. Easy memory

expansion is provided by an active LOW Chip Enable ( $\overline{CE}$ ) and active LOW Output Enable ( $\overline{OE}$ ) and tristate drivers. The device has an automatic power-down feature, reducing the power consumption by more than 95% when deselected.

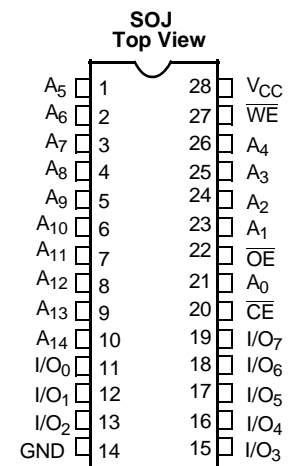
An active LOW Write Enable signal ( $\overline{WE}$ ) controls the writing/reading operation of the memory. When  $\overline{CE}$  and  $\overline{WE}$  inputs are both LOW, data on the eight data input/output pins ( $I/O_0$  through  $I/O_7$ ) is written into the memory location addressed by the address present on the address pins ( $A_0$  through  $A_{14}$ ). Reading the device is accomplished by selecting the device and enabling the outputs,  $\overline{CE}$  and  $\overline{OE}$  active LOW, while  $\overline{WE}$  remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins is present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and Write Enable ( $\overline{WE}$ ) is HIGH. The CY7C1399BN is available in 28-pin standard 300-mil-wide SOJ and TSOP Type I packages.

## Logic Block Diagram



## Pin Configurations



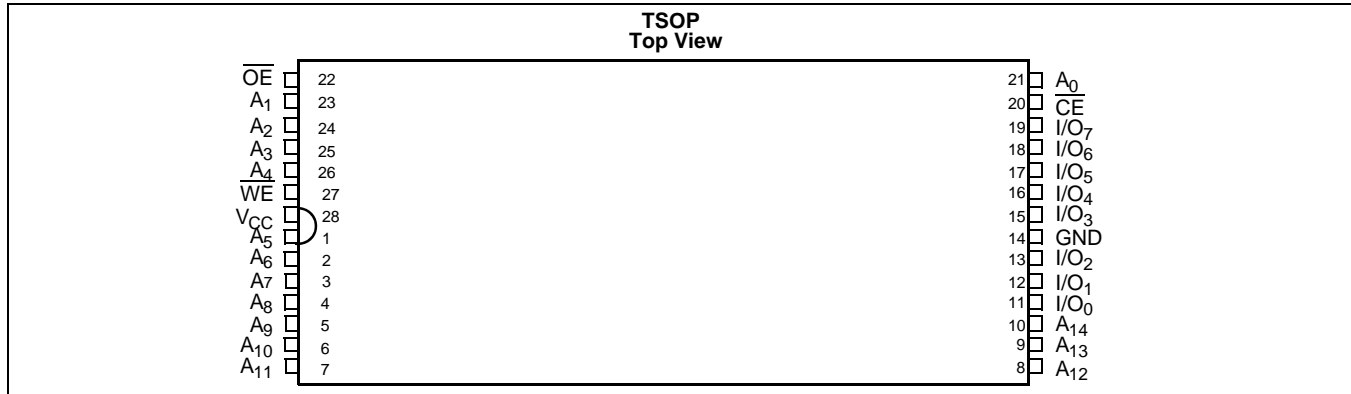
## Selection Guide

|   |                | -12 | -15 |
|---|----------------|-----|-----|
| Maximum Access Time (ns)                |                | 12  | 15  |
| Maximum Operating Current (mA)          |                | 55  | 50  |
| Maximum CMOS Standby Current ( $\mu$ A) | Commercial     | 500 |     |
|   | Commercial (L) | 50  |     |
|   | Industrial     | 500 | 500 |
|   | Automotive-A   |     | 500 |

### Note:

1. For guidelines on SRAM system design, please refer to the 'System Design Guidelines' Cypress application note, available on the internet at [www.cypress.com](http://www.cypress.com).

Pin Configuration



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

- Storage Temperature ..... -65°C to +150°C
- Ambient Temperature with Power Applied ..... -55°C to +125°C
- Supply Voltage on V<sub>CC</sub> to Relative GND<sup>[2]</sup> .... -0.5V to +4.6V
- DC Voltage Applied to Outputs in High Z State<sup>[2]</sup> ..... -0.5V to V<sub>CC</sub> + 0.5V
- DC Input Voltage<sup>[2]</sup> ..... -0.5V to V<sub>CC</sub> + 0.5V

- Output Current into Outputs (LOW) ..... 20 mA
- Static Discharge Voltage ..... >2001V (per MIL-STD-883, Method 3015)
- Latch-Up Current ..... >200 mA

Operating Range

| Range        | Ambient Temperature | V <sub>CC</sub> |
|--------------|---------------------|-----------------|
| Commercial   | 0°C to +70°C        | 3.3V ±300 mV    |
| Industrial   | -40°C to +85°C      |                 |
| Automotive-A | -40°C to +85°C      |                 |

Electrical Characteristics Over the Operating Range<sup>[1]</sup>

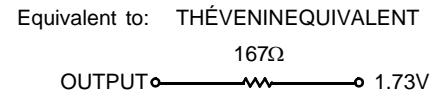
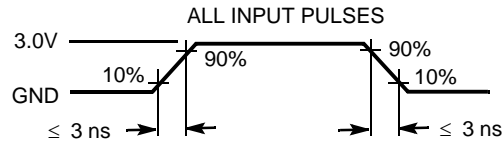
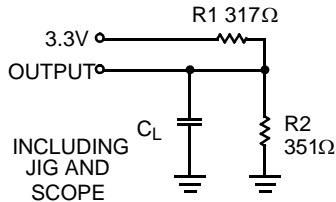
| Parameter        | Description  | Test Conditions   | -12        |                        | -15  |                        | Unit |
|------------------|--|---|------------|------------------------|------|------------------------|------|
|                  |  |   | Min.       | Max.                   | Min. | Max.                   |      |
| V <sub>OH</sub>  | Output HIGH Voltage  | V <sub>CC</sub> = Min., I <sub>OH</sub> = -2.0 mA   | 2.4        |                        | 2.4  |                        | V    |
| V <sub>OL</sub>  | Output LOW Voltage   | V <sub>CC</sub> = Min., I <sub>OL</sub> = 4.0 mA  |            | 0.4                    |      | 0.4                    | V    |
| V <sub>IH</sub>  | Input HIGH Voltage   |   | 2.2        | V <sub>CC</sub> + 0.3V | 2.2  | V <sub>CC</sub> + 0.3V | V    |
| V <sub>IL</sub>  | Input LOW Voltage <sup>[2]</sup>                           |   | -0.3       | 0.8                    | -0.3 | 0.8                    | V    |
| I <sub>IX</sub>  | Input Leakage Current                                      |   | -1         | +1                     | -1   | +1                     | µA   |
| I <sub>OZ</sub>  | Output Leakage Current                                     | GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub> , Output Disabled  | -5         | +5                     | -5   | +5                     | µA   |
| I <sub>CC</sub>  | V <sub>CC</sub> Operating Supply Current                   | V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub> = 1/t <sub>RC</sub>   |            | 55                     |      | 50                     | mA   |
| I <sub>SB1</sub> | Automatic CE Power-Down Current—TTL Inputs                 | Max. V <sub>CC</sub> , $\overline{CE} \geq V_{IH}$ , V <sub>IN</sub> ≥ V <sub>IH</sub> , or V <sub>IN</sub> ≤ V <sub>IL</sub> , f = f <sub>MAX</sub>  | Comm'l     | 5                      |      |                        | mA   |
|                  |  |   | Comm'l (L) | 4                      |      |                        | mA   |
|                  |  |   | Ind'l      | 5                      |      | 5                      | mA   |
|                  |  |   | Auto-A     |                        |      | 5                      | mA   |
| I <sub>SB2</sub> | Automatic CE Power-Down Current—CMOS Inputs <sup>[3]</sup> | Max. V <sub>CC</sub> , $\overline{CE} \geq V_{CC} - 0.3V$ , V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.3V, or V <sub>IN</sub> ≤ 0.3V, WE ≥ V <sub>CC</sub> - 0.3V or WE ≤ 0.3V, f = f <sub>MAX</sub> | Comm'l     | 500                    |      |                        | µA   |
|                  |  |   | Comm'l (L) | 50                     |      |                        | µA   |
|                  |  |   | Ind'l      | 500                    |      | 500                    | µA   |
|                  |  |   | Auto-A     |                        |      | 500                    | µA   |

Notes:

- 2. Minimum voltage is equal to -2.0V for pulse durations of less than 20 ns.
- 3. Device draws low standby current regardless of switching on the addresses.

**Capacitance<sup>[4]</sup>**

| Parameter                   | Description        | Test Conditions   | Max. | Unit |
|-----------------------------|--------------------|---|------|------|
| C <sub>IN</sub> : Addresses | Input Capacitance  | T <sub>A</sub> = 25°C, f = 1 MHz,<br>V <sub>CC</sub> = 3.3V | 5    | pF   |
| C <sub>IN</sub> : Controls  |                    |   | 6    | pF   |
| C <sub>OUT</sub>            | Output Capacitance |   | 6    | pF   |

**AC Test Loads and Waveforms<sup>[5]</sup>**

**Switching Characteristics Over the Operating Range<sup>[5]</sup>**

| Parameter                           | Description                                      | -12  |      | -15  |      | Unit |
|-------------------------------------|--|------|------|------|------|------|
|                                     |  | Min. | Max. | Min. | Max. |      |
| <b>Read Cycle</b>                   |  |      |      |      |      |      |
| t <sub>RC</sub>                     | Read Cycle Time                                  | 12   |      | 15   |      | ns   |
| t <sub>AA</sub>                     | Address to Data Valid                            |      | 12   |      | 15   | ns   |
| t <sub>OHA</sub>                    | Data Hold from Address Change                    | 3    |      | 3    |      | ns   |
| t <sub>ACE</sub>                    | $\overline{CE}$ LOW to Data Valid                |      | 12   |      | 15   | ns   |
| t <sub>DOE</sub>                    | $\overline{OE}$ LOW to Data Valid                |      | 5    |      | 6    | ns   |
| t <sub>LZOE</sub>                   | $\overline{OE}$ LOW to Low Z <sup>[6]</sup>      | 0    |      | 0    |      | ns   |
| t <sub>HZOE</sub>                   | $\overline{OE}$ HIGH to High Z <sup>[6, 7]</sup> |      | 5    |      | 6    | ns   |
| t <sub>LZCE</sub>                   | $\overline{CE}$ LOW to Low Z <sup>[6]</sup>      | 3    |      | 3    |      | ns   |
| t <sub>HZCE</sub>                   | $\overline{CE}$ HIGH to High Z <sup>[6, 7]</sup> |      | 6    |      | 7    | ns   |
| t <sub>PU</sub>                     | $\overline{CE}$ LOW to Power-Up                  | 0    |      | 0    |      | ns   |
| t <sub>PD</sub>                     | $\overline{CE}$ HIGH to Power-Down               |      | 12   |      | 15   | ns   |
| <b>Write Cycle<sup>[8, 9]</sup></b> |  |      |      |      |      |      |
| t <sub>WC</sub>                     | Write Cycle Time                                 | 12   |      | 15   |      | ns   |
| t <sub>SCE</sub>                    | $\overline{CE}$ LOW to Write End                 | 8    |      | 10   |      | ns   |
| t <sub>AW</sub>                     | Address Set-Up to Write End                      | 8    |      | 10   |      | ns   |
| t <sub>HA</sub>                     | Address Hold from Write End                      | 0    |      | 0    |      | ns   |
| t <sub>SA</sub>                     | Address Set-Up to Write Start                    | 0    |      | 0    |      | ns   |
| t <sub>PWE</sub>                    | $\overline{WE}$ Pulse Width                      | 8    |      | 10   |      | ns   |
| t <sub>SD</sub>                     | Data Set-Up to Write End                         | 7    |      | 8    |      | ns   |
| t <sub>HD</sub>                     | Data Hold from Write End                         | 0    |      | 0    |      | ns   |
| t <sub>HZWE</sub>                   | $\overline{WE}$ LOW to High Z <sup>[8]</sup>     |      | 7    |      | 7    | ns   |
| t <sub>LZWE</sub>                   | $\overline{WE}$ HIGH to Low Z <sup>[6]</sup>     | 3    |      | 3    |      | ns   |

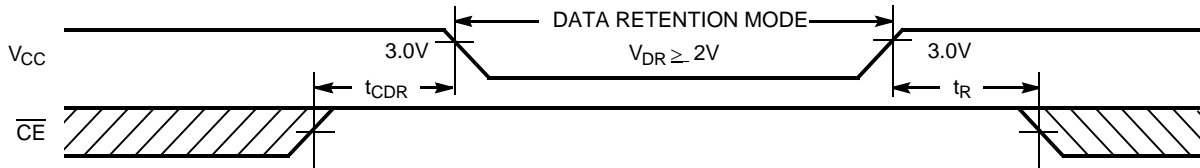
**Notes:**

- Tested initially and after any design or process changes that may affect these parameters.
- Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I<sub>OL</sub>/I<sub>OH</sub> and capacitance C<sub>L</sub> = 30 pF.
- At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub>, t<sub>HZOE</sub> is less than t<sub>LZOE</sub>, and t<sub>HZWE</sub> is less than t<sub>LZWE</sub> for any given device.
- t<sub>HZOE</sub>, t<sub>HZCE</sub>, t<sub>HZWE</sub> are specified with C<sub>L</sub> = 5 pF as in AC Test Loads. Transition is measured ±500 mV from steady state voltage.
- The internal write time of the memory is defined by the overlap of  $\overline{CE}$  LOW and  $\overline{WE}$  LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
- The minimum write cycle time for write cycle #3 ( $\overline{WE}$  controlled,  $\overline{OE}$  LOW) is the sum of t<sub>HZWE</sub> and t<sub>SD</sub>.

**Data Retention Characteristics** (Over the Operating Range - L version only)

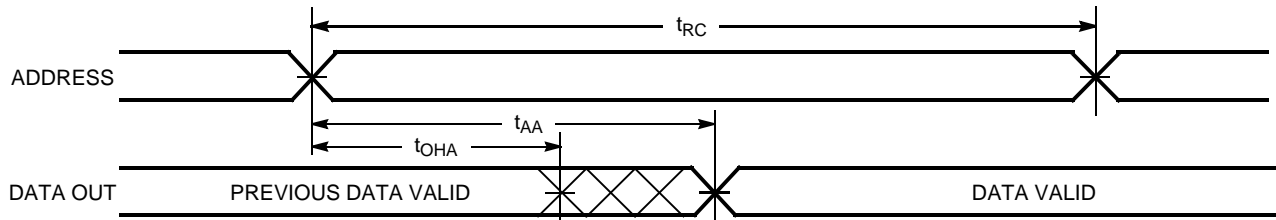
| Parameter  | Description                          | Conditions  | Min.     | Max. | Unit    |
|------------|--------------------------------------|---|----------|------|---------|
| $V_{DR}$   | $V_{CC}$ for Data Retention          |   | 2.0      |      | V       |
| $I_{CCDR}$ | Data Retention Current               | $V_{CC} = V_{DR} = 2.0V,$<br>$CE \geq V_{CC} - 0.3V,$<br>$V_{IN} \geq V_{CC} - 0.3V$ or<br>$V_{IN} \leq 0.3V$ | 0        | 20   | $\mu A$ |
| $t_{CDR}$  | Chip Deselect to Data Retention Time |   | 0        |      | ns      |
| $t_R$      | Operation Recovery Time              |   | $t_{RC}$ |      | ns      |

**Data Retention Waveform**

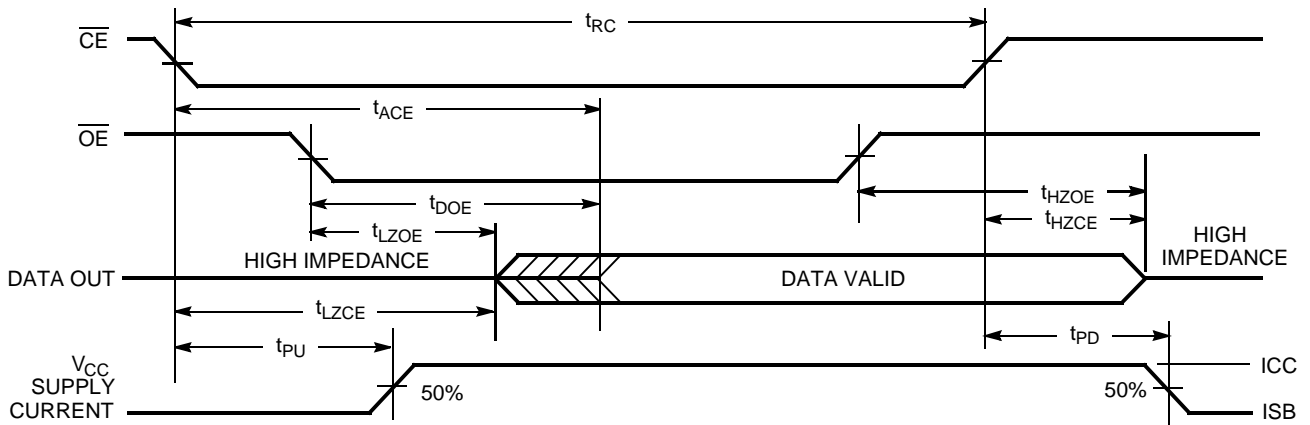


**Switching Waveforms**

**Read Cycle No. 1**<sup>[10, 11]</sup>



**Read Cycle No. 2**<sup>[11, 12]</sup>

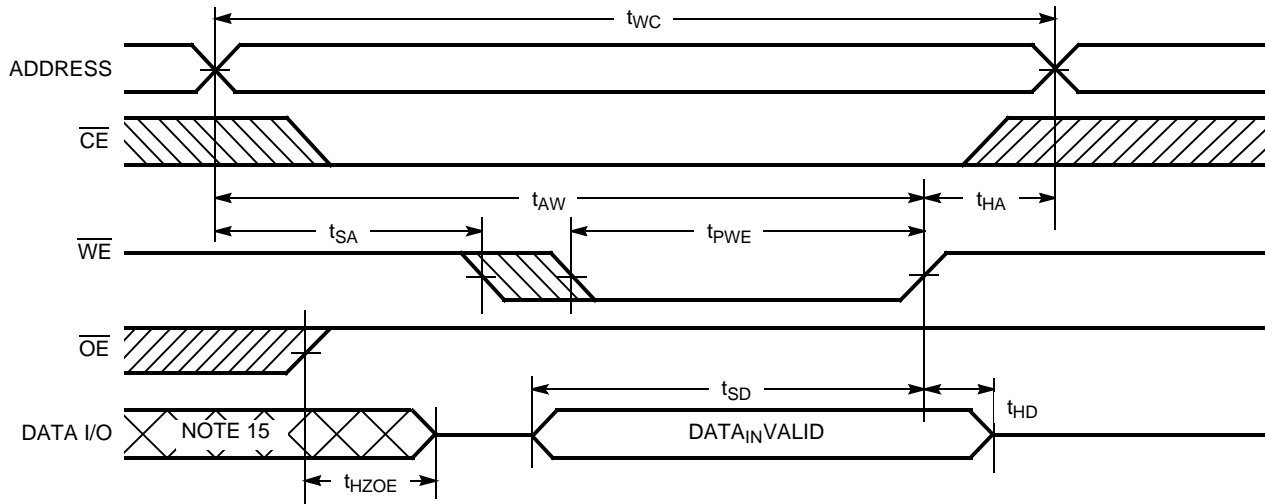


**Notes:**

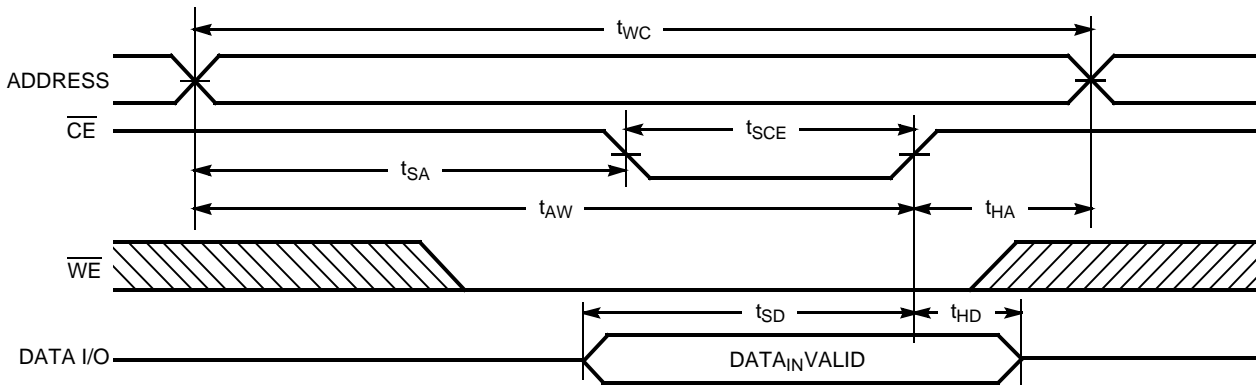
- 10. Device is continuously selected.  $\overline{OE}, \overline{CE} = V_{IL}$ .
- 11.  $\overline{WE}$  is HIGH for read cycle.
- 12. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.

Switching Waveforms (continued)

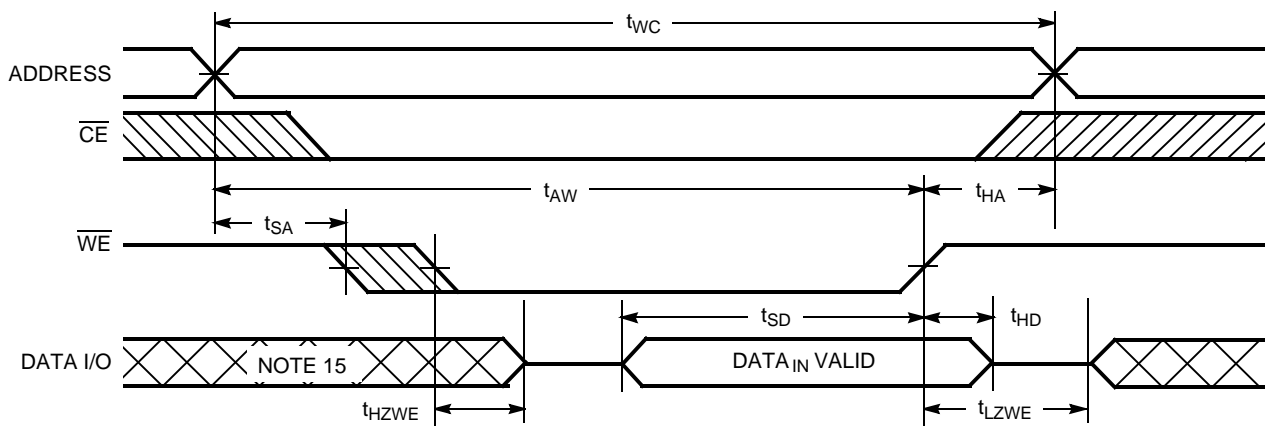
Write Cycle No. 1 ( $\overline{WE}$  Controlled)<sup>[8, 13, 14]</sup>



Write Cycle No. 2 ( $\overline{CE}$  Controlled)<sup>[8, 13, 14]</sup>



Write Cycle No. 3 ( $\overline{WE}$  Controlled,  $\overline{OE}$  LOW)<sup>[9, 14]</sup>



- Notes:**
- 13. Data I/O is high impedance if  $\overline{OE} = V_{IH}$ .
  - 14. If  $\overline{CE}$  goes HIGH simultaneously with  $\overline{WE}$  HIGH, the output remains in a high-impedance state.
  - 15. During this period, the I/Os are in the output state and input signals should not be applied.

**Truth Table**

| $\overline{CE}$ | $\overline{WE}$ | $\overline{OE}$ | Input/Output | Mode                      | Power                |
|-----------------|-----------------|-----------------|--------------|---------------------------|----------------------|
| H               | X               | X               | High Z       | Deselect/Power-Down       | Standby ( $I_{SB}$ ) |
| L               | H               | L               | Data Out     | Read                      | Active ( $I_{CC}$ )  |
| L               | L               | X               | Data In      | Write                     | Active ( $I_{CC}$ )  |
| L               | H               | H               | High Z       | Deselect, Output Disabled | Active ( $I_{CC}$ )  |

**Ordering Information**

Cypress offers other versions of this type of product in many different configurations and features. The following table contains only the list of parts that are currently available.

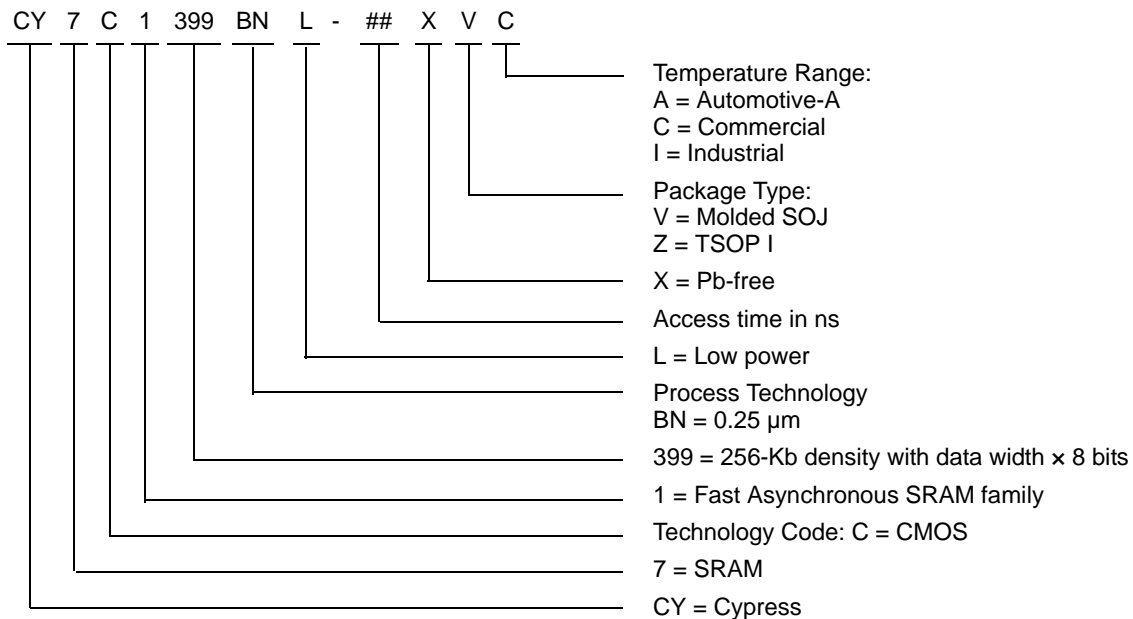
For a complete listing of all options, visit the Cypress website at [www.cypress.com](http://www.cypress.com) and refer to the product summary page at <http://www.cypress.com/products> or contact your local sales representative.

Cypress maintains a worldwide network of offices, solution centers, manufacturer's representatives and distributors. To find the office closest to you, visit us at <http://www.cypress.com/go/datasheet/offices>.

| Speed (ns) | Ordering Code     | Package Diagram | Package Type                 | Operating Range |
|------------|-------------------|-----------------|------------------------------|-----------------|
| 12         | CY7C1399BN-12VXC  | 51-85031        | 28-Lead Molded SOJ (Pb-free) | Commercial      |
|            | CY7C1399BN-12ZXC  | 51-85071        | 28-Lead TSOP I (Pb-free)     |                 |
|            | CY7C1399BNL-12ZXC |                 | 28-Lead TSOP I (Pb-free)     |                 |
|            | CY7C1399BN-12VXI  | 51-85031        | 28-Lead Molded SOJ (Pb-free) | Industrial      |
| 15         | CY7C1399BN-15ZXI  | 51-85071        | 28-Lead TSOP I (Pb-free)     | Industrial      |
|            | CY7C1399BN-15VXA  | 51-85031        | 28-Lead Molded SOJ (Pb-free) | Automotive-A    |

Please contact local sales representative regarding availability of these parts.

**Ordering Code Definitions**

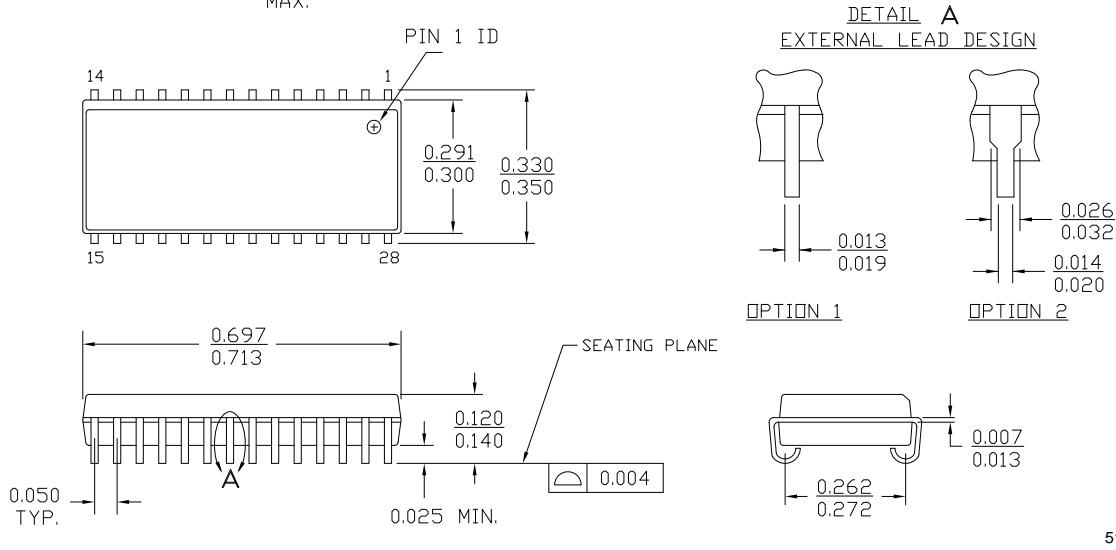


**Package Diagrams**

**28-Lead (300-Mil) Molded SOJ (51-85031)**

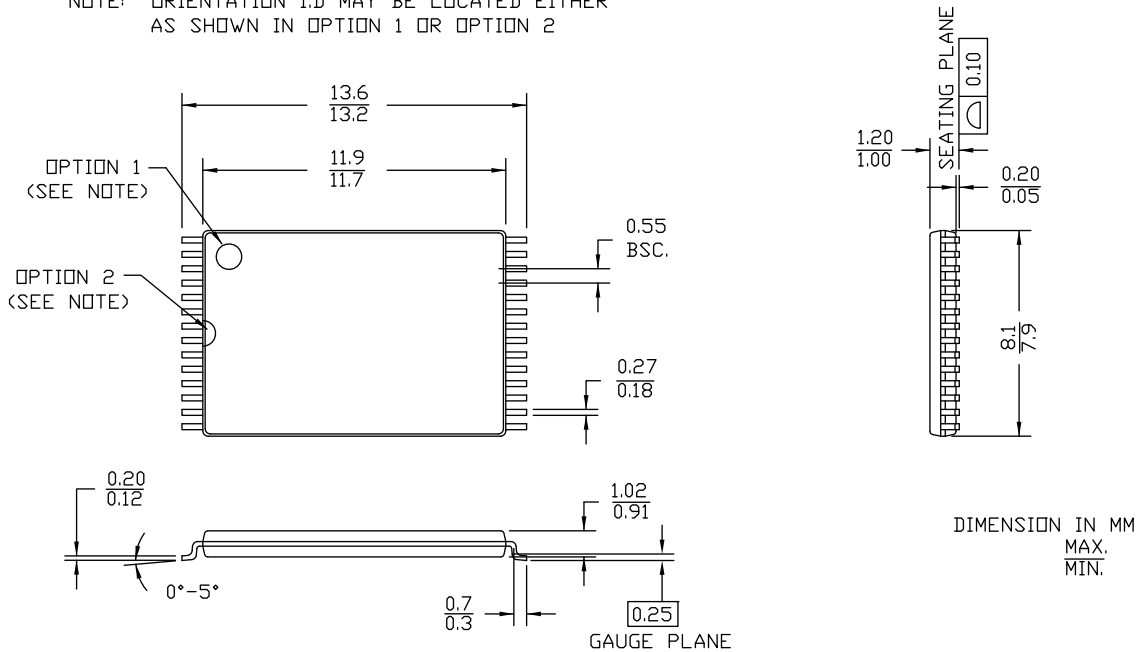
NOTE :

1. JEDEC STD REF MO088
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH  
MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.006 in (0.152 mm) PER SIDE
3. DIMENSIONS IN INCHES MIN.  
MAX.



**28-Lead TSOP 1 (8x13.4 mm) (51-85071)**

NOTE: ORIENTATION I.D MAY BE LOCATED EITHER AS SHOWN IN OPTION 1 OR OPTION 2



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**Document History Page**

| Document Title: CY7C1399BN 256K (32K x 8) Static RAM<br>Document Number: 001-06490 |         |            |                 |   |
|--|---------|------------|-----------------|---|
| REV.   | ECN NO. | ISSUE DATE | ORIG. OF CHANGE | DESCRIPTION OF CHANGE   |
| **   | 423877  | See ECN    | NXR             | New Data Sheet  |
| *A   | 498575  | See ECN    | NXR             | Added Automotive-A range<br>Removed I <sub>OS</sub> parameter from DC Electrical Characteristics table<br>Updated Ordering Information table. |
| *B   | 2896382 | 03/19/2010 | AJU             | Removed obsolete part numbers from Ordering Information table and updated package diagrams.   |
| *C   | 3053362 | 10/08/2010 | PRAS            | Removed pruned part numbers CY7C1399BNL-15VXC and CY7C1399BNL-15VXCT. Added Ordering Code Definitions.  |

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